

ON Semiconductor®

# FDB8160-F085 N-Channel PowerTrench® MOSFET

**30V**, **80A**, **1.8m**Ω

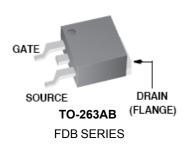
#### **Features**

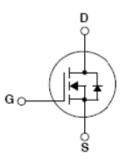
- Typ  $r_{DS(on)}$  = 1.5m $\Omega$  at  $V_{GS}$  = 10V,  $I_D$  = 80A
- Typ  $Q_{q(10)}$  = 187nC at  $V_{GS}$  = 10V
- Low Miller Charge
- Low Qrr Body Diode
- UIS Capability (Single Pulse and Repetitive Pulse)
- Qualified to AEC Q101
- RoHS Compliant

## **Applications**

- 12V Automotive Load Control
- Starter/Alternator Systems
- Electronic Power Steering Systems
- DC/DC converter







Units

Max

## **MOSFET Maximum Ratings** $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Ratings	Units
$V_{DSS}$	Drain to Source Voltage	30	V
$V_{GS}$	Gate to Source Voltage	±20	V
I <sub>D</sub>	Drain Current Continuous (T <sub>C</sub> < 160°C, V <sub>GS</sub> = 10V)	80	Α
	Pulsed	See Figure 4	А
E <sub>AS</sub>	Single Pulse Avalanche Energy (Note 1)	1290	mJ
D	Power Dissipation	254	W
$P_{D}$	Derate above 25°C	1.7	W/°C
$T_J$ , $T_{STG}$	Operating and Storage Temperature	-55 to +175	°C

#### **Thermal Characteristics**

$R_{\theta JC}$	Maximum Thermal Resistance Junction to Case	0.59	°C/W
IR <sub>0.1A</sub>	Maximum Thermal Resistance Junction to Ambient TO-263,1in <sup>2</sup> copper pad area	43	°C/W

## **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDB8160	FDB8160-F085	TO-263AB	330mm	24mm	800 units

#### Electrical Characteristics T<sub>J</sub> = 25°C unless otherwise noted

**Parameter** 

Off Characteristics							
B <sub>VDSS</sub>	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	30	-	-	V	
	Zero Gate Voltage Drain Current	$V_{DS} = 24V, V_{GS} = 0V$	-	-	1	μА	
DSS	Zero Gate Voltage Drain Current	$T_{J} = 150^{\circ}C$	-	-	250	μΑ	
I <sub>GSS</sub>	Gate to Source Leakage Current	$V_{GS} = \pm 20V$	-	-	±100	nA	

**Test Conditions** 

Min

Тур

#### **On Characteristics**

Symbol

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	2	2.9	4	V
r <sub>DS(on)</sub> Drain to Source On Resistance	$I_D = 80A, V_{GS} = 10V$	-	1.5	1.8	mΩ	
	Drain to Source On Resistance	I <sub>D</sub> = 80A, V <sub>GS</sub> = 10V, T <sub>J</sub> = 175°C	-	2.6	3.1	mΩ

#### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	\\ - 45\\ \\ - 6	N/	-	11825	-	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0V, f = 1MHz		-	1810	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			-	1240	-	pF
Rg	Gate Resistance	f = 1MHz		-	1.75	-	Ω
$Q_{g(TOT)}$	Total Gate Charge at 10V	V <sub>GS</sub> = 0 to 10V		-	187	243	nC
$Q_{g(th)}$	Threshold Gate Charge	$V_{GS} = 0$ to $2V$	V <sub>DD</sub> = 15V	-	20	26	nC
$Q_{gs}$	Gate to Source Gate Charge		I <sub>D</sub> = 80A	-	43	-	nC
Q <sub>gs2</sub>	Gate Charge Threshold to Plateau			-	23	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge			-	57	-	nC

Units

ns

ns

Max

137

## **Electrical Characteristics** $T_J = 25^{\circ}C$ unless otherwise noted

**Parameter** 

Switching Characteristics								
t <sub>on</sub>	Turn-On Time		-	-	60	ns		
t <sub>d(on)</sub>	Turn-On Delay Time		-	17.2	-	ns		
t <sub>r</sub>	Turn-On Rise Time	V <sub>DD</sub> = 15V, I <sub>D</sub> = 80A,	-	18.9	-	ns		
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS}$ = 10V, $R_{GS}$ = 1.3 $\Omega$	-	60	-	ns		

**Test Conditions** 

Min

Тур

27

#### **Drain-Source Diode Characteristics**

Turn-Off Fall Time

Turn-Off Time

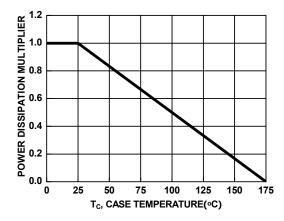
$V_{SD}$	Source to Drain Diode voltage	I <sub>SD</sub> = 80A	-	0.9	1.25	V
		I <sub>SD</sub> = 40A	1	0.8	1.0	V
t <sub>rr</sub>	Reverse Recovery Time	$I_{F} = 80A, dI_{SD}/dt = 100A/\mu s$	-	48	62	ns
Q <sub>rr</sub>	Reverse Recovery Charge		-	42	55	nC

Symbol

1: Starting T<sub>J</sub> = 25°C, L = 0.63mH, I<sub>AS</sub> = 64A 2: Pulse width = 100s.

This product has been designed to meet the extreme test conditions and environment demanded by the automotive industry. For a copy of the requirements, see AEC Q101 at: http://www.aecouncil.com/ All ON Semiconductor products are manufactured, assembled and tested under ISO9000 and QS9000 quality systems certification.

## **Typical Characteristics**



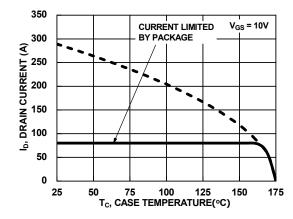
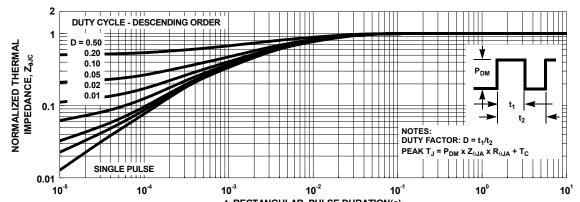


Figure 1. Normalized Power Dissipation vs Case Temperature

Figure 2. Maximum Continuous Drain Current vs Case Temperature



t, RECTANGULAR PULSE DURATION(s)
Figure 3. Normalized Maximum Transient Thermal Impedance

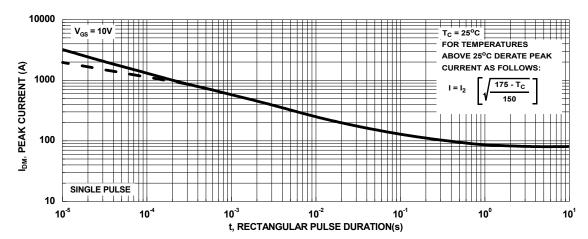


Figure 4. Peak Current Capability

## **Typical Characteristics**

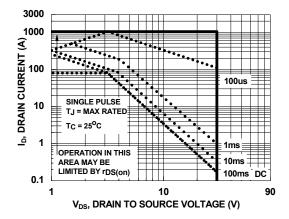
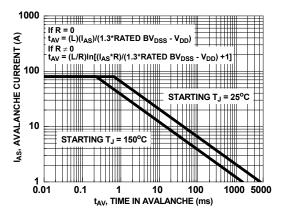


Figure 5. Forward Bias Safe Operating Area



NOTE: Refer to ON Semiconductor Application Notes AN7514 and AN7515

Figure 6. Unclamped Inductive Switching Capability

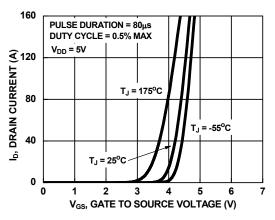


Figure 7. Transfer Characteristics

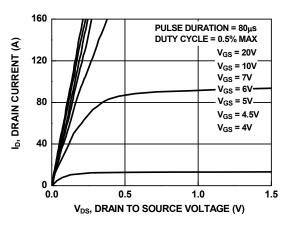


Figure 8. Saturation Characteristics

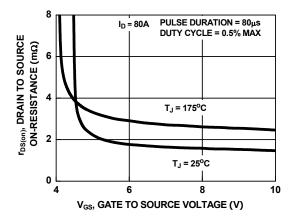


Figure 9. Drain to Source On-Resistance Variation vs Gate to Source Voltage

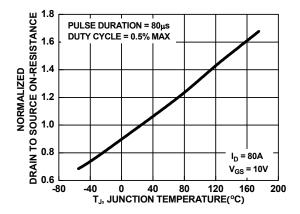


Figure 10. Normalized Drain to Source On Resistance vs Junction Temperature

## **Typical Characteristics**

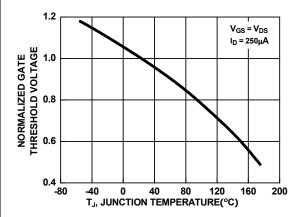


Figure 11. Normalized Gate Threshold Voltage vs Junction Temperature

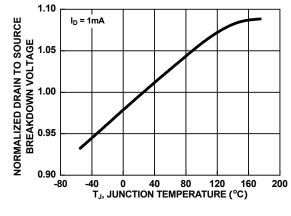


Figure 12. Normalized Drain to Source Breakdown Voltage vs Junction Temperature

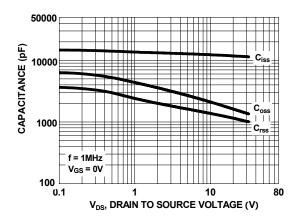


Figure 13. Capacitance vs Drain to Source Voltage

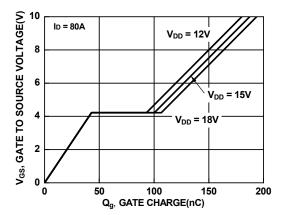


Figure 14. Gate Charge vs Gate to Source Voltage

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